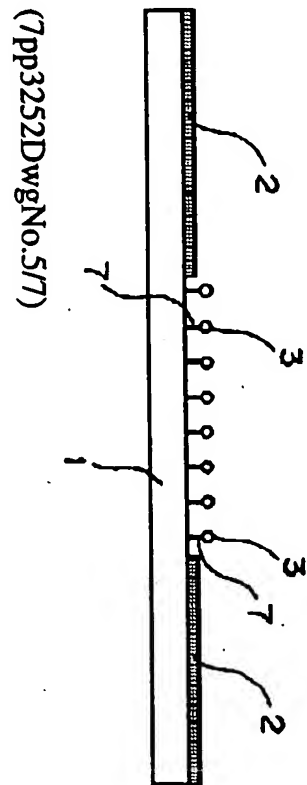


A

<p>2002-388122/42 L01 M13 (L03) MUA 2000.08.29 MITSUBOSHI BELTING LTD *JP 2002068782-A 2000.08.29 2000-258425(+2000JP-258425) (2002.03.08) C03C 17/38, C23C 18/18, 18/31 Pattern plating method for glass substrate, involves fixing metal microparticle to silane connecting agent on glass substrate and removing resist film from masked substrate region C2002-109732</p>	<p>L(1-G4, 1-G5, 4-C6B, 4-C12D) M(13-H)</p>
<p><u>NOVELTY</u> The glass substrate regions except a desired pattern region is masked by a resist film (2). The glass substrate surface (1) is treated by a silane connecting agent (7) which has a functional group chosen from a ureido group. A metal microparticle (3) is fixed to the silane connecting agent. A non-electrolytic plating is given to the glass substrate and the resist film is removed from the masked region.</p> <p><u>DETAILED DESCRIPTION</u> An INDEPENDENT CLAIM is included for glass substrate.</p> <p><u>USE</u> For pattern plating on glass substrate (claimed).</p>	<p><u>ADVANTAGE</u> The plating film and glass substrate show excellent adhesion, as a metal fine plating film can be provided as a catalyst nucleus for plating of the metal microparticle.</p> <p><u>DESCRIPTION OF DRAWING</u> The figure shows a glass substrate on which a metal particle is fixed through a silane connecting agent fixed to the substrate. Glass substrate surface 1 Resist film 2 Metal microparticle 3 Silane connecting agent 7</p> <p>JP 2002068782-A+</p>



(7pp3252DwgNo.5/7)